Integrated Circuit Systems, Inc.

ICS9248-150

Frequency Generator for Multi - Processor Servers

Recommended Application:
ServerWorks Grand Champion Systems.

Output Features:
- 8 - Differential CPU Clock Pairs @ 3.3V
- 1 - 3V 33MHz PCI clocks
- 1 - 48MHz clock
- 1 - Inverted 48MHz clock
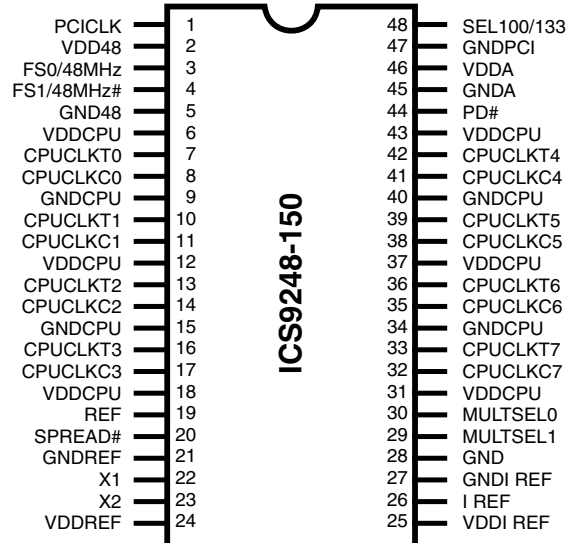- 1 - 14.318 reference output

Features:
- Up to 200MHz frequency support
- Support power management: Power Down Mode
- Supports Spread Spectrum modulation: 0 to -0.5% down spread.
- Uses external 14.318MHz crystal
- Select logic for Differential Swing Control, Test mode, Tristate, Power down, Spread Spectrum.
- External resistor for current reference
- FS pins for frequency select

Key Specifications:
- PCI Output jitter <500ps
- CPU Output jitter <200ps
- 48MHz Output jitter <350ps
- REF Output jitter < 1000ps

Pin Configuration

PCICLK	1		48	SEL100/133
VDD48	2		47	GNDPCI
FS0/48MHz	3		46	VDDA
FS1/48MHz#	4		45	GNDA
GND48	5		44	PD#
VDDCPU	6		43	VDDCPU
CPUCLKT0	7		42	CPUCLKT4
CPUCLKC0	8		41	CPUCLKC4
GNDCPU	9		40	GNDCPU
CPUCLKT1	10		39	CPUCLKT5
CPUCLKC1	11		38	CPUCLKC5
VDDCPU	12		37	VDDCPU
CPUCLKT2	13		36	CPUCLKT6
CPUCLKC2	14		35	CPUCLKC6
GNDCPU	15		34	GNDCPU
CPUCLKT3	16		33	CPUCLKT7
CPUCLKC3	17		32	CPUCLKC7
VDDCPU	18		31	VDDCPU
REF	19		30	MULTSEL0
SPREAD#	20		29	MULTSEL1
GNDREF	21		28	GND
X1	22		27	GNDI REF
X2	23		26	I REF
VDDREF	24		25	VDDI REF

48-Pin SSOP and TSSOP

Functionality

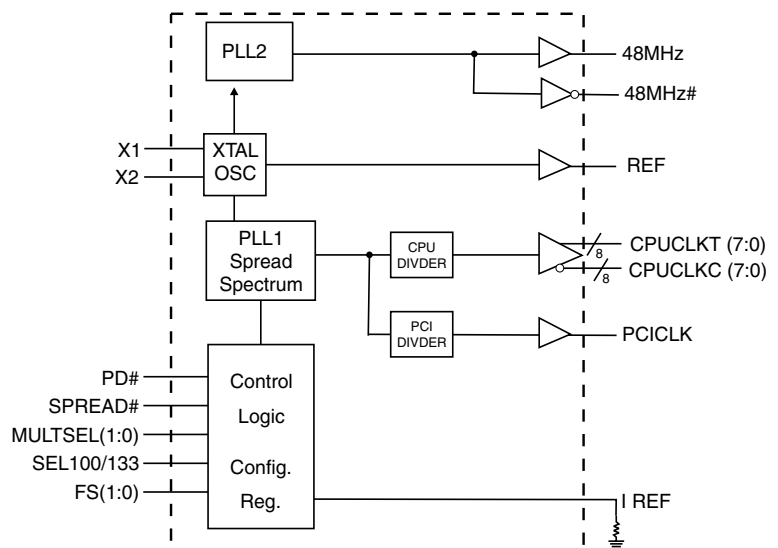| SEL133/100	FS0	FS1	Function
0	0	0	Active 100MHz
0	0	1	100MHz Test Mode
0	1	0	100MHz Test Mode
0	1	1	Tristate all outputs
1	0	0	Active 133MHz
1	0	1	133MHz Test Mode
1	1	0	Active 200MHz
1	1	1	Reserved

Analog Power Groups

VDD48, GND48 = 48MHz, PLL2
VDDA = VDD (core supply voltage 3.3V)
GNDA = Ground for core supply

Digital Power Group

VDDREF, GNDREF = REF, Xtal

Block Diagram

ICS9248-150

General Description

The **ICS9248-150** is a main clock for ServerWorks Grand Champion Systems.

Spread spectrum typically reduces system EMI by 8dB to 10dB. This simplifies EMI qualification without resorting to board design iterations or costly shielding. The ICS9248-150 employs a proprietary closed loop design, which tightly controls the percentage of spreading over process and temperature variations.

Pin Configuration

PIN NUMBER	PIN NAME	TYPE	DESCRIPTION
1	PCICLK	OUT	PCI clock output
2, 6, 12, 18, 24, 31, 37, 43,	VDD	PWR	3.3V power supply
3	FS0	IN	Frequency select pin
	48MHz	OUT	48MHz clock output
4	FS1	IN	Frequency select pin
	48MHz#	OUT	Inverted 48MHz clock output
5, 9, 15, 21, 28, 34, 40, 47	GND	PWR	Ground pins for 3.3V supply
33, 36, 39, 42, 16, 13, 10, 7	CPUCLKT (7:0)	OUT	"True" clocks of differential pair CPU outputs. These are current outputs and external resistors are required for voltage bias.
32, 35, 38, 41, 17, 14, 11, 8	CPUCLKC (7:0)	OUT	"Complementory" clocks of differential pair CPU outputs. These are current outputs and external resistors are required for voltage bias.
19	REF	OUT	Reference output 14.318MHz
20	SPREAD#	IN	Invokes Spread Spectrum functionality on the Differential host clocks, Active Low
22	X1	X2 Crystal Input	14.318MHz Crystal input
23	X2	X1 Crystal Output	14.318MHz Crystal output
25, 46	VDDI REF VDDA,	PWR	Analog power supply 3.3V
26	I REF	OUT	This pin establishes the reference current for the CPUCLK pairs. This pin takes a fixed precision resistor tied to ground in order to establish the required current.
29, 30	MULTSEL(1:0)	IN	CPU swing select inputs
44	PD#	IN	Invokes power-down mode. Active Low.
27, 45	GNDI REF GNDA	PWR	Analog Ground pins for 3.3V supply
48	SEL100/133	IN	CPU Frequency Select. Low=100MHz, High=133MHz

Truth Table

SEL 133/100	FS0	FS1	CPUCLK MHz	PCICLK MHZ	48 MHz
0	0	0	100	33	48
0	0	1	100	33	Disable
0	1	0	100	Disable	Disable
0	1	1	Tristate	Tristate	Tristate
1	0	0	133	33	48
1	0	1	133	33	Disable
1	1	0	200	33	48
1	1	1	TCLK/2	TCLK/8	TCLK/2

CPUCLK Buffer Configuration

	Conditions	Configuration	Load	Min	Max
Iout	Vdd = nominal (3.30V)	All combinations of M0, M1 and Rr shown in table below	Nominal test load for given configuration	-7% I nominal	+7% I nominal
Iout	Vdd = 3.30 ± 5%	All combinations of M0, M1 and Rr shown in table below	Nominal test load for given configuration	-12% I nominal	+12% I nominal

CPUCLK Swing Select Functions

MULTSEL0	MULTSEL1	Board Target Trace/Term Z	Reference R, Iref= Vdd/(3*Rr)	Output Current	Voh @ Z, Iref=2.32mA
0	0	60 ohms	Rr = 475 1% Iref = 2.32mA	Ioh = 5*Iref	0.71V @ 60
0	0	50 ohms	Rr = 475 1% Iref = 2.32mA	Ioh = 5*Iref	0.59V @ 50
0	1	60 ohms	Rr = 475 1% Iref = 2.32mA	Ioh = 6*Iref	0.85V /2 60
0	1	50 ohms	Rr = 475 1% Iref = 2.32mA	Ioh = 6*Iref	0.71V @ 50
1	0	60 ohms	Rr = 475 1% Iref = 2.32mA	Ioh = 4*Iref	0.56V @ 60
1	0	50 ohms	Rr = 475 1% Iref = 2.32mA	Ioh = 4*Iref	0.47V @ 50
1	1	60 ohms	Rr = 475 1% Iref = 2.32mA	Ioh = 7*Iref	0.99V @ 60
1	1	50 ohms	Rr = 475 1% Iref = 2.32mA	Ioh = 7*Iref	0.82V @ 50
0	0	30 (DC equiv)	Rr = 221 1% Iref = 5mA	Ioh = 5*Iref	0.75V @ 30
0	0	25 (DC equiv)	Rr = 221 1% Iref = 5mA	Ioh = 5*Iref	0.62V @ 20
0	1	30 (DC equiv)	Rr = 221 1% Iref = 5mA	Ioh = 6*Iref	0.90V @ 30
0	1	25 (DC equiv)	Rr = 221 1% Iref = 5mA	Ioh = 6*Iref	0.75V @ 20
1	0	30 (DC equiv)	Rr = 221 1% Iref = 5mA	Ioh = 4*Iref	0.60 @ 20
1	0	25 (DC equiv)	Rr = 221 1% Iref = 5mA	Ioh = 4*Iref	0.5V @ 20
1	1	30 (DC equiv)	Rr = 221 1% Iref = 5mA	Ioh = 7*Iref	1.05V @ 30
1	1	25 (DC equiv)	Rr = 221 1% Iref = 5mA	Ioh = 7*Iref	0.84V @ 20

Absolute Maximum Ratings

Supply Voltage . . . . 5.5 V
Logic Inputs . . . . GND –0.5 V to V_{DD} +0.5 V
Ambient Operating Temperature . . . . 0°C to +70°C
Case Temperature . . . . 115°C
Storage Temperature . . . . –65°C to +150°C

Stresses above those listed under *Absolute Maximum Ratings* may cause permanent damage to the device. These ratings are stress specifications only and functional operation of the device at these or any other conditions above those listed in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect product reliability.

Electrical Characteristics - Input/Supply/Common Output Parameters

T_A = 0 - 70C; Supply Voltage V_{DD} = 3.3 V +/-5%

PARAMETER	SYMBOL	CONDITIONS	MIN	TYP	MAX	UNITS
Input High Voltage	V_{IH}		2		V_{DD}+0.3	V
Input Low Voltage	V_{IL}		V_{SS}-0.3		0.8	V
Input High Current	I_{IH}	$V_{IN} = V_{DD}$	-5		5	μA
Input Low Current	I_{IL1}	$V_{IN} = 0$ V; Inputs with no pull-up resistors	-5			μA
	I_{IL2}	$V_{IN} = 0$ V; Inputs with pull-up resistors	-200			
Operating Supply Current	$I_{DD3.3OP}$	$C_L = 0$ pF; Select @ 100 MHz		181	250	mA
Powerdown Current	$I_{DD3.3PD}$	$C_L = 0$ pF; Input address to VDD or GND		52	60	mA
Input Frequency	F_i	$V_{DD} = 3.3$ V		14.318		MHz
Pin Inductance	L_{pin}				7	nH
Input Capacitance[1]	C_{IN}	Logic Inputs			5	pF
	C_{OUT}	Output pin capacitance			6	pF
	C_{INX}	X1 & X2 pins	27		45	pF
Transition time[1]	T_{trans}	To 1st crossing of target frequency			3	ms
Settling time[1]	T_s	From 1st crossing to 1% target frequency			3	ms
Clk Stabilization[1]	T_{STAB}	From $V_{DD} = 3.3$ V to 1% target frequency			3	ms
Delay[1]	t_{PZH}, t_{PZL}	Output enable delay (all outputs)	1		10	ns
	t_{PHZ}, t_{PLZ}	Output disable delay (all outputs)	1		10	ns

[1]Guaranteed by design, not 100% tested in production.

Electrical Characteristics - CPU

T_A = 0 - 70C; VDD=3.3V +/-5%; C_L = 10-20 pF (unless otherwise specified)

PARAMETER	SYMBOL	CONDITIONS	MIN	TYP	MAX	UNITS
Output Impedance	R_{DSP2B}[1]	V_O = V_{DD}*(0.5)		714		Ω
Output Impedance	R_{DSN2B}[1]	V_O = V_{DD}*(0.5)		714		Ω
Output High Voltage	V_{OH2B}	I_{OH} = -1 mA	2			V
Output Low Voltage	V_{OL2B}	I_{OL} = 1 mA			0.4	V
Output High Current	I_{OH2B}[2]	$V_{OH@MIN}$ = 1.0 V, $V_{OH@MAX}$ = 2.375 V	-27		-27	mA
Output Low Current	I_{OL2B}[2]	$V_{OL@MIN}$ = 1.2 V, $V_{OL@MAX}$ = 0.3 V	27		30	mA
Rise Time	t_{r2B}[1]	V_{OL} = 20%, V_{OH} = 80%	175	324	700	ps
Fall Time	t_{f2B}[1]	V_{OH} = 80%, V_{OL} = 20%	175	501	700	ps
Diff. Crossover Voltag	V_x	V_{DD} = 3.3V	45	50	55	%
Duty Cycle	d_{t2B}[1]	V_T = 50%	45	51.2	55	%
Skew CPUT0:7	t_{sk2B}[1]	V_T = 50%		83.8	100	ps
Skew CPU C0:7	t_{sk2B}[1]	V_T = 50%		78.5	100	ps
Jitter	$t_{jcyc-cyc}$[1]	V_T = 50%		86	150	ps

[1] Guaranteed by design, not 100% tested in production.

[2] I_{OWT} can be varied and is selectable thru the MULTSEL pin.

Electrical Characteristics - REF

T_A = 0 - 70C; VDD=3.3V +/-5%; C_L = 10-20 pF (unless otherwise specified)

PARAMETER	SYMBOL	CONDITIONS	MIN	TYP	MAX	UNITS
Output Frequency	F_{O1}					MHz
Output Impedance	R_{DSP1}[1]	V_O = V_{DD}*(0.5)	20	48	60	Ω
Output High Voltage	V_{OH}[1]	I_{OH} = -1 mA	2.4			V
Output Low Voltage	V_{OL}[1]	I_{OL} = 1 mA			0.4	V
Output High Current	I_{OH}[1]	$V_{OH@MIN}$ = 1.0 V, $V_{OH@MAX}$ = 3.135 V	-29		-23	mA
Output Low Current	I_{OL}[1]	$V_{OL@MIN}$ = 1.95 V, $V_{OL@MAX}$ = 0.4 V	29		27	mA
Rise Time	t_{r1}[1]	V_{OL} = 0.4 V, V_{OH} = 2.4 V	1	1.6	4	ns
Fall Time	t_{f1}[1]	V_{OH} = 2.4 V, V_{OL} = 0.4 V	1	2.4	4	ns
Duty Cycle	d_{t1}[1]	V_T = 1.5 V	45	53.5	55	%
Skew	t_{sk1}[1]	V_T = 1.5 V			N/A	ps
Jitter	$t_{jcyc-cyc}$[1]	V_T = 1.5 V		305	1000	ps

[1] Guaranteed by design, not 100% tested in production.

Electrical Characteristics - PCI

$T_A = 0 - 70C$; VDD=3.3V +/-5%; C_L = 10-30 pF (unless otherwise specified)

PARAMETER	SYMBOL	CONDITIONS	MIN	TYP	MAX	UNITS
Output Frequency	F_{O1}					MHz
Output Impedance	$R_{DSP1}{}^1$	$V_O = V_{DD}*(0.5)$	12	33	55	Ω
Output High Voltage	$V_{OH}{}^1$	$I_{OH} = -1$ mA	2.4			V
Output Low Voltage	$V_{OL}{}^1$	$I_{OL} = 1$ mA			0.55	V
Output High Current	$I_{OH}{}^1$	$V_{OH@MIN} = 1.0$ V, $V_{OH@MAX} = 3.135$ V	-33		-33	mA
Output Low Current	$I_{OL}{}^1$	$V_{OL@MIN} = 1.95$ V, $V_{OL@MAX} = 0.4$ V	30		38	mA
Rise Time	$t_{r1}{}^1$	$V_{OL} = 0.4$ V, $V_{OH} = 2.4$ V	0.5	1.2	2	ns
Fall Time	$t_{f1}{}^1$	$V_{OH} = 2.4$ V, $V_{OL} = 0.4$ V	0.5	1.2	2	ns
Duty Cycle	$d_{t1}{}^1$	$V_T = 1.5$ V	45	49.9	55	%
Skew	$t_{sk1}{}^1$	$V_T = 1.5$ V			500	ps
Jitter	$t_{jcyc-cyc}{}^1$	$V_T = 1.5$ V		139.7	500	ps

[1]Guaranteed by design, not 100% tested in production.

Electrical Characteristics - 48MHz

$T_A = 0 - 70C$; VDD=3.3V +/-5%; C_L = 10-20 pF (unless otherwise specified)

| PARAMETER	SYMBOL	CONDITIONS	MIN	TYP	MAX	UNITS
Output Frequency	F_{O1}					MHz
Output Impedance	$R_{DSP1}{}^1$	$V_O = V_{DD}*(0.5)$	20	48	60	Ω
Output High Voltage	$V_{OH}{}^1$	$I_{OH} = -1$ mA	2.4			V
Output Low Voltage	$V_{OL}{}^1$	$I_{OL} = 1$ mA			0.4	V
Output High Current	$I_{OH}{}^1$	$V_{OH@MIN} = 1.0$ V, $V_{OH@MAX} = 3.135$ V	-29		-23	mA
Output Low Current	$I_{OL}{}^1$	$V_{OL@MIN} = 1.95$ V, $V_{OL@MAX} = 0.4$ V	29		27	mA
Rise Time	$t_{r1}{}^1$	$V_{OL} = 0.4$ V, $V_{OH} = 2.4$ V	1	1.3	4	ns
Fall Time	$t_{f1}{}^1$	$V_{OH} = 2.4$ V, $V_{OL} = 0.4$ V	1	1.6	4	ns
Duty Cycle	$d_{t1}{}^1$	$V_T = 1.5$ V	45	52.5	55	%
Skew	$t_{sk1}{}^1$	$V_T = 1.5$ V			N/A	ps
Jitter	$t_{jcyc-cyc}{}^1$	$V_T = 1.5$ V		175	350	ps

[1]Guaranteed by design, not 100% tested in production.

PD# Timing Diagram

The power down selection is used to put the part into a very low power state without turning off the power to the part. PD# is an asynchronous active low input. This signal needs to be synchronized internal to the device prior to powering down the clock synthesizer.

Internal clocks are not running after the device is put in power down. When PD# is active low all clocks need to be driven to a low value and held prior to turning off the VCOs and crystal. The power up latency needs to be less than 3 mS. The power down latency should be as short as possible but conforming to the sequence requirements shown below.
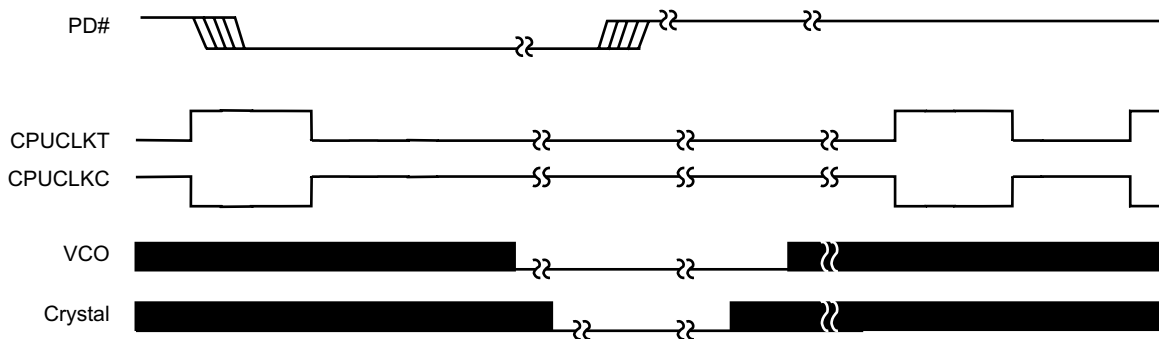
Notes:
1. As shown, the outputs Stop Low on the next falling edge after PD# goes low.
2. PD# is an asynchronous input and metastable conditions may exist. This signal is synchronized inside this part.
3. The shaded sections on the VCO and the Crystal signals indicate an active clock.
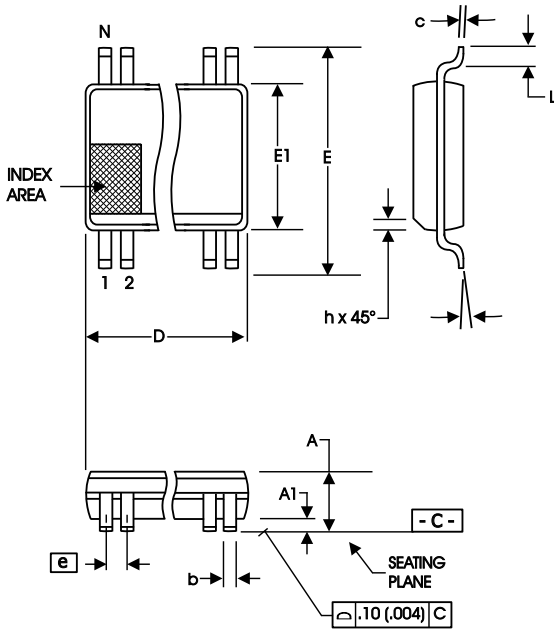
300 mil SSOP Package

SYMBOL	In Millimeters COMMON DIMENSIONS		In Inches COMMON DIMENSIONS	
	MIN	MAX	MIN	MAX
A	2.41	2.80	.095	.110
A1	0.20	0.40	.008	.016
b	0.20	0.34	.008	.0135
c	0.13	0.25	.005	.010
D	SEE VARIATIONS		SEE VARIATIONS	
E	10.03	10.68	.395	.420
E1	7.40	7.60	.291	.299
e	0.635 BASIC		0.025 BASIC	
h	0.38	0.64	.015	.025
L	0.50	1.02	.020	.040
N	SEE VARIATIONS		SEE VARIATIONS	
α	0°	8°	0°	8°

VARIATIONS

N	D mm.		D (inch)	
	MIN	MAX	MIN	MAX
48	15.75	16.00	.620	.630

Reference Doc.: JEDEC Publication 95, MO-118

10-0034

Ordering Information

ICS9248yF-150-T

Example:

ICS XXXX y F - PPP - T

Designation for tape and reel packaging

Pattern Number (2 or 3 digit number for parts with ROM code patterns)

Package Type
   F=SSOP

Revision Designator (will not correlate with datasheet revision)

Device Type

Prefix
   ICS, AV = Standard Device

Third party brands and names are the property of their respective owners.
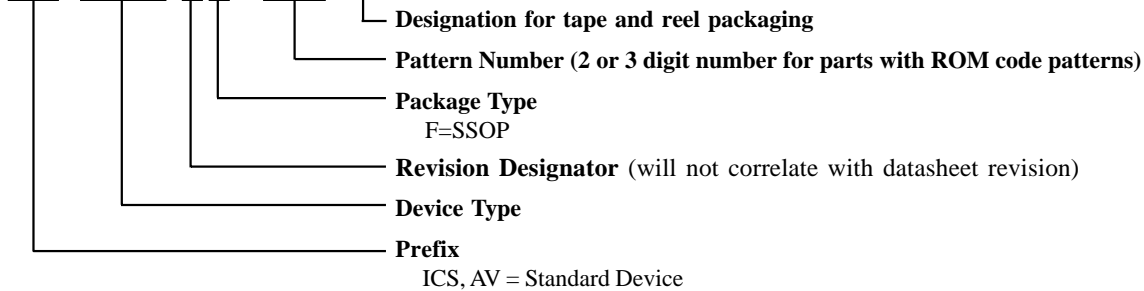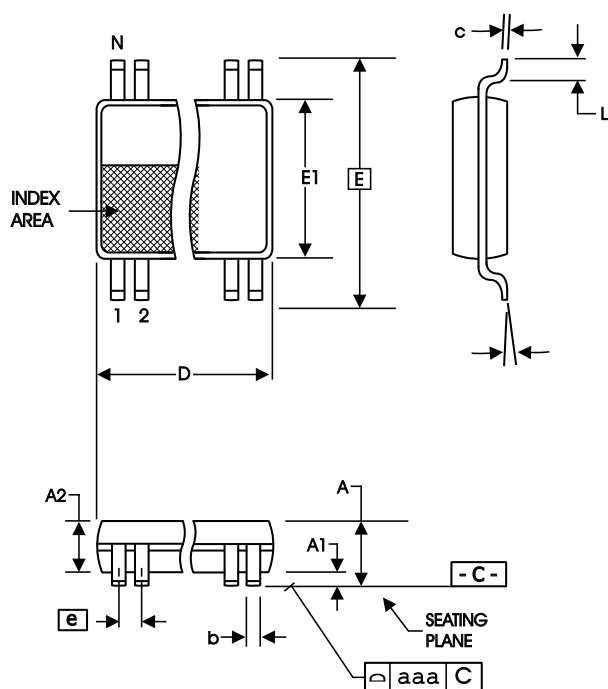
SYMBOL	In Millimeters COMMON DIMENSIONS		In Inches COMMON DIMENSIONS	
	MIN	MAX	MIN	MAX
A	--	1.20	--	.047
A1	0.05	0.15	.002	.006
A2	0.80	1.05	.032	.041
b	0.17	0.27	.007	.011
c	0.09	0.20	.0035	.008
D	SEE VARIATIONS		SEE VARIATIONS	
E	8.10 BASIC		0.319 BASIC	
E1	6.00	6.20	.236	.244
e	0.50 BASIC		0.020 BASIC	
L	0.45	0.75	.018	.030
N	SEE VARIATIONS		SEE VARIATIONS	
α	0°	8°	0°	8°
aaa	--	0.10	--	.004

VARIATIONS

N	D mm.		D (inch)	
	MIN	MAX	MIN	MAX
48	12.40	12.60	.488	.496

Reference Doc.: JEDEC Publication 95, MO-153

10-0039

6.10 mm. Body, 0.50 mm. pitch TSSOP
(240 mil)   (0.020 mil)

Ordering Information

ICS9248yG-150-T

Example:

ICS XXXX y G - PPP - T

Designation for tape and reel packaging

Pattern Number (2 or 3 digit number for parts with ROM code patterns)

Package Type
G=TSSOP

Revision Designator (will not correlate with datasheet revision)

Device Type

Prefix
ICS, AV = Standard Device